

What is claimed is:

1. A component container for storing and transporting components that are used for the manufacturing of semiconductor devices, comprising:

an inner shell created using polymethylmethacrylate (PPMA), said inner shell having an outer surface, said inner shell having been provided with a cavity, said inner shell being provided with a front surface, said front surface being provided with a means for accessing said cavity of said inner shell, said cavity having been provided with a means for positioning said component inside said cavity;

a metallic layer having a first and a second surface, said first and said second surface being coated with a layer of polyimide, said metallic layer being attached to said outer surface of said inner shell, completely covering said inner shell with said metallic layer, creating a two layered shell having a cavity, said two layered shell further having outside surfaces, said outside surfaces of said two layered shell having first dimensions in an X, Y and Z direction;

an outer shell, created using polymethylmethacrylate (PPMA), said outer shell having a cavity, said outer shell being provided with a front surface, said front surface being provided with a means for accessing said cavity of said outer shell, said outer shell further having inside surfaces, said inside surfaces of

said outer shell having second dimensions in an X, Y and Z direction, said second dimensions of said outer shell being essentially equal to said first dimensions of said two layered shell, thereby completely surrounding said two layered shell with said outer shell.

2. The component container of claim 1, said metallic layer comprising aluminum.

3. The component container of claim 1, said means for positioning said component inside said cavity comprising:

at least one support post having a surface in a plane, said at least one support post comprising a high-resistivity material; and

at least one platform, said at least one platform being positioned above said at least one support post, said at least one platform being in contact with said at least one support post, said at least one platform being positioned in said plane of said surface of said at least one support post, said at least one support post comprising a high-resistivity material.

4. A method of creating a component container for storing and transporting components that are used for the manufacturing of semiconductor devices, comprising the steps of:

providing an inner shell, said inner shell comprising polymethylmethacrylate (PPMA), said inner shell having an outer surface, said inner shell having been provided with a cavity, said inner shell having been provided with a front surface, said front surface having been provided with a means for accessing said cavity of said inner shell, said cavity having been provided with a means for positioning said component inside said cavity;

providing a metallic layer having a first and a second surface, said first and said second surface having been coated with a layer of polyimide;

attaching said metallic layer to said outer surface of said inner shell, completely covering said inner shell with said metallic layer, creating a two layered shell having a cavity, said two layered shell further having outside surfaces, said outside surfaces of said two layered shell having first dimensions in an X, Y and Z direction;

providing an outer shell, said outer shell comprising polymethylmethacrylate (PPMA), said outer shell having a cavity, said outer shell having been provided with a front surface, said front surface having been provided with a means for accessing said cavity of said outer shell, said outer shell further having inside surfaces, said inside surfaces of said outer shell having second dimensions in an X, Y and Z direction, said second dimensions of said outer shell being essentially equal to said

first dimensions of said two layered shell, thereby completely surrounding said two layered shell with said outer shell.

5. The method of claim 4, said metallic layer comprising aluminum.

6. The method of claim 1, said providing said means for positioning said component inside said cavity comprising the steps of:

providing at least one support post having a surface in a plane, said at least one support post comprising a high-resistivity material;

providing at least one platform; and

positioning said at least one platform above said at least one support post, said at least one platform being in contact with said at least one support post, said at least one platform being positioned in said plane of said surface of said at least one support post, said at least one support post comprising a high-resistivity material.

7. A component container for storing and transporting components that are used for the manufacturing of semiconductor devices, comprising:

surfaces, said surface comprising at least two layers of high resistivity material, at least one layer of low resistivity material having been interspersed between said at least layers of high resistivity material;

a cavity, said cavity having been provided with a means for positioning said component inside said cavity; and

at least one of said surfaces having been provided with means for accessing said cavity.

8. The component container of claim 7, said high resistivity material comprising polymethylmethacrylate (PPMA).

9. The component container of claim 7, said low resistivity material comprising metal.

10. The component container of claim 7, said low resistivity material comprising aluminum.

11. The component container of claim 7, surfaces of said low resistivity material additionally being coated with polyester.

12. The component container of claim 7, said means for positioning said component inside said cavity comprising:

at least one support post having a surface in a plane, said
at least one support post comprising a high-resistivity material;
and

at least one platform, said at least one platform being
positioned above said at least one support post, said at least
one platform being in contact with said at least one support
post, said at least one platform being positioned in said plane
of said surface of said at least one support post, said at least
one support post comprising a high-resistivity material.

13. A method for creating a component container for storing and
transporting components that are used for the manufacturing of
semiconductor devices, comprising the steps of:

creating surfaces for said component container, said
surfaces comprising at least two layers of high resistivity
material, at least one layer of low resistivity material having
been interspersed between said at least layers of high
resistivity material;

creating a cavity surrounded by said surfaces;

providing said cavity with a means for positioning said
component inside said cavity; and

providing at least one of said surfaces of said component
container with means for accessing said cavity.

14. The method of claim 13, said high resistivity material comprising polymethylmethacrylate (PPMA).

15. The method of claim 13, said low resistivity material comprising metal.

16. The method of claim 13, said low resistivity material comprising aluminum.

17. The method of claim 13, surfaces of said low resistivity material additionally being coated with polyester.

18. The method of claim 13, said providing said cavity with a means for positioning said component inside said cavity comprises the steps of:

providing at least one support post having a surface in a plane, said at least one support post comprising a high-resistivity material; and

providing at least one platform; and

positioning said at least one platform above said at least one support post, said at least one platform being in contact with said at least one support post, said at least one platform being positioned in said plane of said surface of said at least

one support post, said at least one support post comprising a high-resistivity material.

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one support post, said at least one support post comprising a high-resistivity material.